

**Amendments to the Claims:**

This listing of the claims will replace all prior versions and listings of claims in the application:

**Listing of Claims:**

Claim 1 (canceled)

Claim 2 (previously presented): A semiconductor device comprising:

a BGA substrate having one principal plane furnished with a large number of solder balls;

a first semiconductor chip having a first side and an opposite side, said first semiconductor chip including bumps and active regions formed on the first side, said first semiconductor chip being attached to another principal plane of said BGA substrate through the bumps; and

a first chip capacitor attached to the active regions of said first semiconductor chip, wherein a thickness of said first chip capacitor is less than a thickness of the bumps.

Claim 3 (previously presented): A semiconductor device comprising:

a BGA substrate having one principal plane furnished with a large number of solder balls;

a first semiconductor chip having a first side and an opposite side, said first semiconductor chip including bumps and active regions formed on the first side, said first semiconductor chip being attached to another principal plane of said BGA substrate through the bumps; and

a first chip capacitor attached to the opposite side of said first semiconductor chip, wherein said first semiconductor chip further includes vias extending from the active

regions to the opposite side of said first semiconductor chip, and said first chip capacitor is electrically connected to the active regions through the vias.

Claim 4 (withdrawn): The semiconductor device according to claim 2, further comprising:

a second semiconductor chip mounted on said opposite side of said active regions of said first semiconductor chip, said second semiconductor chip being electrically connected to said BGA substrate by metal wires; and

a second chip capacitor attached to said second semiconductor chip as well as a first chip capacitor attached to said active region of said first semiconductor chip, said second chip capacitor serving to reduce power source noise.

Claim 5 (canceled)

Claim 6 (withdrawn): The semiconductor device according to claim 2, further comprising:

a conductive radiator attached to said another principal plane of said BGA substrate, said conductive radiator covering said first semiconductor chip; and

a shield plane incorporated in said BGA substrate, said shield plane constituting a shield of said first semiconductor chip in combination with said conductive radiator;

wherein said conductive radiator and said shield plane are connected to ground potential.

Claim 7 (withdrawn): The semiconductor device according to claim 6, further comprising a heat transfer member interposed between said opposite side of said active regions of said semiconductor chip and said conductive radiator.

Claim 8 (canceled)

Claim 9 (withdrawn): The semiconductor device according to claim 6, further comprising a radiating fin attached to an external surface of said conductive radiator.

Claims 10-15 (canceled)

Claim 16 (previously presented): The semiconductor device according to claim 2, wherein said first chip capacitor is disposed among the bumps.

Claim 17 (new): The semiconductor device according to claim 3, further comprising:

a conductive radiator attached to said another principal plane of said BGA substrate, said conductive radiator covering said semiconductor chip; and

a shield plane incorporated in said BGA substrate, said shield plane constituting a shield of said semiconductor chip in combination with said conductive radiator;

wherein said conductive radiator and said shield plane are connected to ground potential.

Claim 18 (new): The semiconductor device according to claim 17, further comprising a radiating fin attached to an external surface of said conductive radiator.

Claim 19 (new): The semiconductor device according to claim 3, further comprising a mold resin covering said semiconductor chip and chip capacitor.

Claim 20 (new): The semiconductor device according to claim 3, further comprising an under-fill resin for sealing said bumps.